

# SK 25 UT 16p



## Antiparallel Thyristor Module

### SK 25 UT 16p

#### Features\*

- Compact Design
- One screw mounting
- Heat transfer and insulation through direct copper bonded aluminium oxide ceramic (DBC)
- Glass passivated thyristor chip
- Up to 1600V reverse voltage
- UL recognized file no. E 63 532

#### Typical Applications

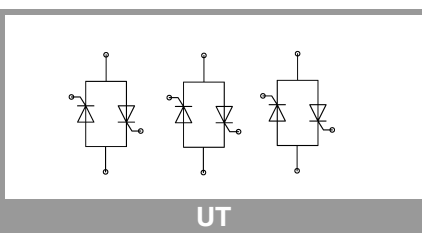
- Soft starter
- Light control (studios, theater)
- Temperature control

| Absolute Maximum Ratings |                         |                         |             |                  |
|--------------------------|-------------------------|-------------------------|-------------|------------------|
| Symbol                   | Conditions              |                         | Values      | Unit             |
| Thyristor 1              |                         |                         |             |                  |
| I <sub>T(AV)</sub>       | sin 180°                | T <sub>s</sub> = 25 °C  | 31          | A                |
|                          |                         | T <sub>s</sub> = 70 °C  | 22          | A                |
| I <sub>TSM</sub>         | 10 ms                   | T <sub>j</sub> = 25 °C  | 370         | A                |
|                          |                         | T <sub>j</sub> = 130 °C | 280         | A                |
| i <sup>2</sup> t         | 10 ms                   | T <sub>j</sub> = 25 °C  | 685         | A <sup>2</sup> s |
|                          |                         | T <sub>j</sub> = 130 °C | 392         | A <sup>2</sup> s |
| V <sub>RRM</sub>         |                         |                         | 1600        | V                |
| V <sub>DRM</sub>         |                         |                         | 1600        | V                |
| (di/dt) <sub>cr</sub>    | T <sub>j</sub> = 130 °C |                         | 50          | A/μs             |
| (dv/dt) <sub>cr</sub>    | T <sub>j</sub> = 130 °C |                         | 1000        | V/μs             |
| T <sub>j</sub>           |                         |                         | -40 ... 125 | °C               |

| Absolute Maximum Ratings |  |             |      |
|--------------------------|--|-------------|------|
| Symbol                   | Conditions   | Values      | Unit |
| <b>Module</b>            |  |             |      |
| $I_{t(RMS)}$             | $\Delta T_{terminal}$ at PCB joint = 30 K, per pin | 35          | A    |
| $T_{stg}$                | module without TIM                                 | -40 ... 125 | °C   |
| $V_{isol}$               | AC, sinusoidal, t = 1 min                          | 2500        | V    |

| Characteristics    |   |      |      |       |      |
|--------------------|---|------|------|-------|------|
| Symbol             | Conditions  | min. | typ. | max.  | Unit |
| <b>Thyristor 1</b> |   |      |      |       |      |
| $V_T$              | $T_j = 25\text{ °C}$ , $I_T = 25\text{ A}$                            |      |      | 1.26  | V    |
| $V_{T(TO)}$        | $T_j = 130\text{ °C}$   |      |      | 0.85  | V    |
| $r_T$              | $T_j = 130\text{ °C}$   |      |      | 13.90 | mΩ   |
| $I_{DD}; I_{RD}$   | $T_j = 130\text{ °C}$ , $V_{DD} = V_{DRM}$ ; $V_{RD} = V_{RRM}$       |      |      | 6     | mA   |
| $t_{gd}$           | $T_j = 25\text{ °C}$ , $I_G = 1\text{ A}$ , $di_G/dt = 1\text{ A/μs}$ |      | 1    |       | μs   |
| $t_{gr}$           | $V_D = 0.67 \cdot V_{DRM}$  |      | 2    |       | μs   |
| $t_q$              | $T_j = 130\text{ °C}$   |      | 150  |       | μs   |
| $I_H$              | $T_j = 25\text{ °C}$  | 220  |      |       | mA   |
| $I_L$              | $T_j = 25\text{ °C}$ , $R_G = 33\text{ Ω}$                            | 550  |      |       | mA   |
| $V_{GT}$           | $T_j = 25\text{ °C}$ , d.c.   | 2    |      |       | V    |
| $I_{GT}$           | $T_j = 25\text{ °C}$ , d.c.   | 100  |      |       | mA   |
| $V_{GD}$           | $T_j = 130\text{ °C}$ , d.c.  |      |      | 0.25  | V    |
| $I_{GD}$           | $T_j = 130\text{ °C}$ , d.c.  |      |      | 6     | mA   |
| $R_{th(j-s)}$      | per thyristor, $\lambda_{paste} = 0.8\text{ W/(mK)}$ , sin. 180°      |      | 1.7  |       | K/W  |

| Characteristics |             |      |      |      |      |
|-----------------|-------------|------|------|------|------|
| Symbol          | Conditions  | min. | typ. | max. | Unit |
| <b>Module</b>   |             |      |      |      |      |
| $M_s$           | to heatsink | 2.25 |      | 2.5  | Nm   |
| w               | weight      |      | 30   |      | g    |



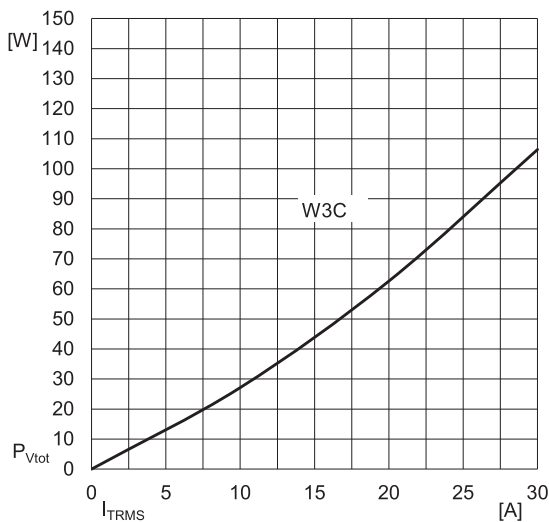


Fig. 1: Power dissipation per module vs. rms current

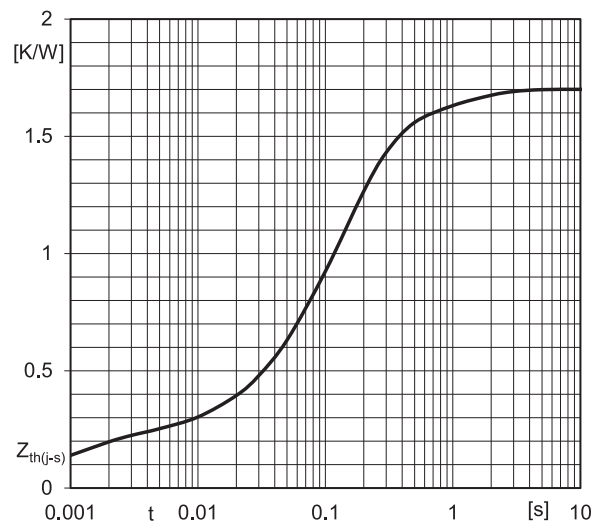


Fig. 2: Typ. transient thermal impedance

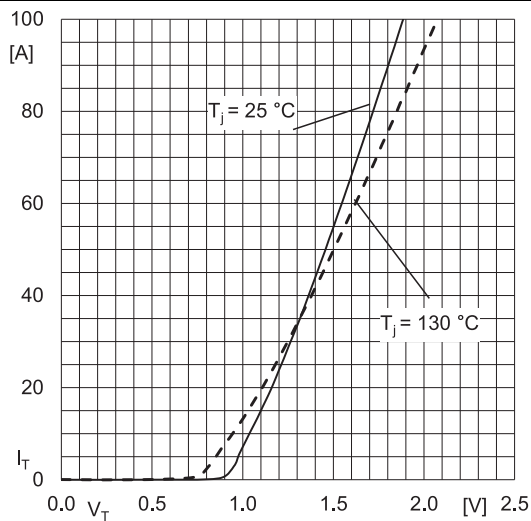


Fig. 3: Typ. forward characteristic of single thyristor

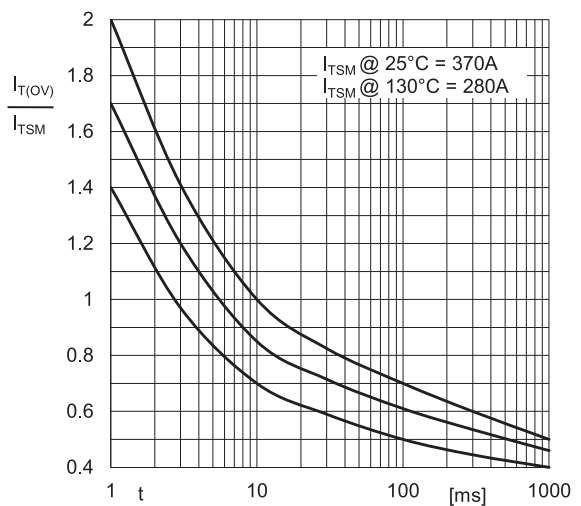


Fig. 4 : Surge overload current vs. time

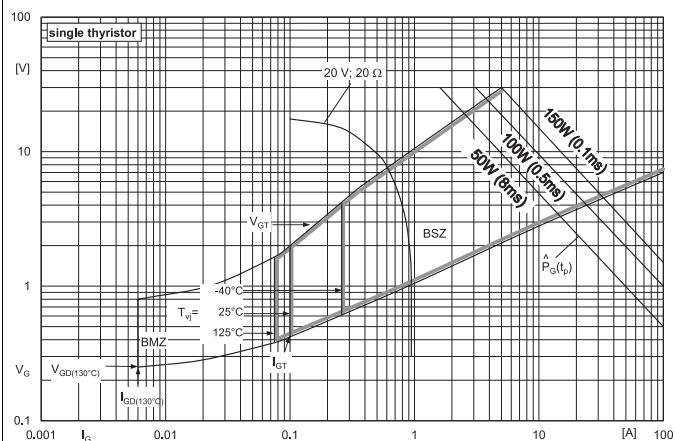
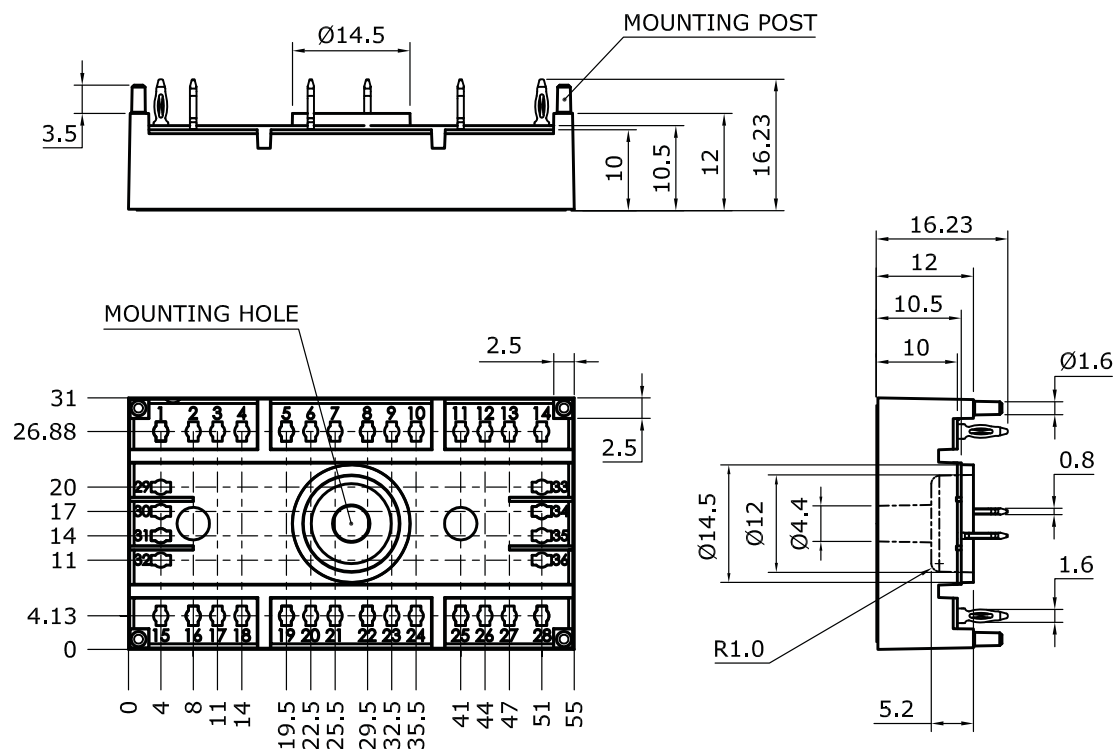


Fig. 5: Gate trigger characteristic

Dimensions: mm

Tolerance system: ISO 2768-m



Suggested drilled hole diameter for terminal pins in the circuit board:

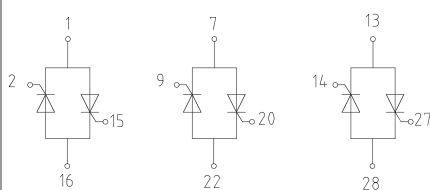
- minimum: 1.575 mm
- typical: 1.6 mm
- maximum: 1.625 mm

Suggested hole diameter for the mounting post in the circuit board:

- 2 mm

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SEMITOP 3 Press-Fit



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This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

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